

Title (en)  
POLISHING PAD AND METHOD FOR MANUFACTURING THE POLISHING PAD

Title (de)  
POLIERKISSEN UND VERFAHREN ZUR HERSTELLUNG DES POLIERKISSENS

Title (fr)  
TAMPON DE POLISSAGE ET PROCÉDÉ DE FABRICATION DU TAMPON DE POLISSAGE

Publication  
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Application  
**EP 09804969 A 20090804**

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Abstract (en)  
[origin: EP2316614A1] A polishing pad is disclosed which is less likely to cause scratches, and has an excellent planarization performance and polishing stability. In one aspect, the invention provides a polishing pad comprising an ultrafine fiber-entangled body formed of ultrafine fibers having an average fineness of 0.01 to 0.8 dtex, and a polymeric elastomer. The polymeric elastomer has a glass transition temperature of -10°C or below, storage moduli at 23°C and 50°C of 90 to 900 MPa, and a water absorption ratio, when saturated with water at 50°C, of 0.2 to 5 mass%.

IPC 8 full level  
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